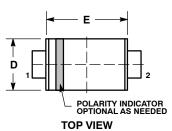
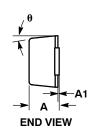
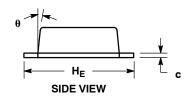


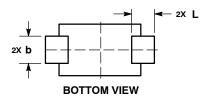
SOD-123FL **CASE 498** ISSUE D

DATE 10 MAY 2013

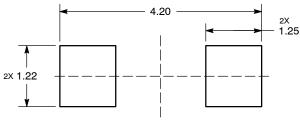








RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.

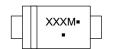
- DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH.

 DIMENSIONS D AND J ARE TO BE MEASURED ON FLAT SECTION

 OF THE LEAD: BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.90	0.95	0.98	0.035	0.037	0.039
A1	0.00	0.05	0.10	0.000	0.002	0.004
b	0.70	0.90	1.10	0.028	0.035	0.043
С	0.10	0.15	0.20	0.004	0.006	0.008
D	1.50	1.65	1.80	0.059	0.065	0.071
E	2.50	2.70	2.90	0.098	0.106	0.114
L	0.55	0.75	0.95	0.022	0.030	0.037
HE	3.40	3.60	3.80	0.134	0.142	0.150
θ	0°	-	8°	0°	-	8°

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

= Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

DOCUMENT NUMBER:	98AON11184D	Electronic versions
STATUS:	ON SEMICONDUCTOR STANDARD	accessed directly from versions are unconficient to accept the conficient acceptance of the conficient
NEW STANDARD:		
DESCRIPTION:	SOD-123FL	

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^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



DOCUMENT	NUMBER:
98AON11184	D

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ISSUE	REVISION	DATE
0	RELEASED FOR PRODUCTION. REQ. BY D. CULBERTSON.	18 FEB 2002
А	ADDED NOMINAL VALUES AND UPDATED GENERIC MARKING DIAGRAM. REQ. BY HONG XIAO.	27 MAY 2005
В	ADMINISTRATIVE CHANGE TO REFLECT THE COMPLETE DOCUMENT HISTORY. REQ. BY V. ILAS.	28 JUN 2010
С	MODIFED SOLDER FOOTPRINT TO MILLIMETER VALUES. REQ. BY D. TRUHITTE.	11 DEC 2012
D	CHANGED DIMENSION A MAX MM VALUE FROM 1.00 TO 0.98. REQ. BY D. TRUHITTE.	10 MAY 2013

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